

PROTECTIVE FILM FORMING APPARATUS

ABSTRACT OF THE DISCLOSURE

In a protective film forming apparatus 2, a supply unit 23 includes: a resin nozzle 24 that supplies a water-soluble resin to a center of an upper surface of a wafer W of a work set WS; a water nozzle 25 that supplies water to an upper surface of a ring frame F of the work set WS; and an air nozzle 26 that supplies air to the upper surface of the ring frame F of the work set WS. The resin nozzle 24, the water nozzle 25, and the air nozzle 26 are disposed on an arm 27 extending in a direction of the holding surface of a holding table 20. The air nozzle 26 is disposed downstream of the water nozzle 25 in a direction of rotation of the holding table 20. Therefore, when a water-soluble protective film is formed on the upper surface of the wafer W, the upper surface of the ring frame F can also be cleaned efficiently, and the water-soluble resin is not left on the upper surface of the ring frame F.

[Figure 2]